APPLICA	BLE STAN	DARD										
	Operating temperature range Voltage Current		-55°C to 85°C		temp	Storage temperature range Operating or storage humidity range			-10°C TO 50°C (packed condition)			
RATING			30V AC/DC					Re	Relative humidity 90%MAX(not dev			
			0.20A Appli			icable cable t=0.12±0.02mm, gold p			olating	9		
			SPEC	IFIC	ATIOI	NS						
IT	EM		TEST METHOD				F	REQU	IREMENTS	QT	АТ	
CONSTR	UCTION	-I										
General examination		Visually and by measuring instrument.				According to drawing.				×	×	
Marking		Confirmed visually.				(note 1,2)				×	×	
ELECTR	ICAL CHA	RACTE	RISTICS									
Voltage prod	of	90V AC f	or 1 min.			No flas	hover or	break	down.	×	×	
Insulation resistance		100V DC.				50MΩ MIN.				×	×	
Contact resistance		20mV AC MAX, 1mA.			300mΩ MAX. Including FPC, FFC bulk resistance (L=8mm)				×	×		
MECHAN	IICAL CHA	RACTE	RISTICS									
		Frequency 10 to 55 Hz, half amplitude 0.75 mm, for 10 cycles in 3 axial directions.			① No electrical discontinuity of 1μs.			×	_			
Shock		981 m/s ² , duration of pulse 6 ms at 3 times in 3 both axial directions.			② Contact resistance: 300mΩ MAX. ③ No damage, crack and loose parts.			×	_			
Mechanical of	operation		10 times insertions and extractions.			 Contact resistance: 300mΩ MAX. No damage, crack and loose parts. 			×	_		
FPC retention		(thickness	d by applicable FPC. s of FPC shall be t=0.12mm a	t initial o	ndition)	Direction	on of ins	ertion:	2.2N MIN(<i>note 3,5</i>)	×	_	
ENVIRO	NMENTAL	CHARA	ACTERISTICS			I				1		
Corrosion salt mist		Exposed at 35±2°C, 5% salt water spray for 96h.			 Contact resistance: 300mΩ MAX. No damage, crack and loose parts. No evidence of corrosion which affects connector's operation. 			×	_			
Rapid change of temperature		Temperature-55 \rightarrow +15 _{TO} +35 \rightarrow +85 \rightarrow +15 _{TO} +35°C Time 30 \rightarrow 2 _{TO} 3 \rightarrow 30 \rightarrow 2 _{TO} 3 min			① Contact resistance: 300mΩ MAX.				×	_		
Damp heat		Under 5 cycles. Exposed at 40±2°C,			② Insulation resistance: 50MΩ MIN.③ No damage, crack and loose parts.							
(steady state))	relative humidity 90 to 95%, 96h.							×			
Damp heat,cyclic		Exposed at -10 to +65°C, relative humidity 90 to 96%, 10 cycles, total 240h.			 Contact resistance: 300mΩ MAX. Insulation resistance: 1MΩ MIN. (at high humidity) Insulation resistance: 50MΩ MIN. (at dry) No damage, crack and loose parts. 			×				
Dry heat		Exposed at 85±2°C, 96h.			① Contact resistance: 300mΩ MAX.				×	_		
Cold		Exposed at -55±3°C, 96h.			② No damage, crack and loose parts.				×			
Sulphur dioxide [JIS C 60068-2-42]		relative h	bosed at 40±2°C, ative humidity 80±5%, ±5ppm for 96h.			 Contact resistance: 300mΩ MAX. No damage, crack and loose parts. No evidence of corrosion which affects connector's operation. 			×	_		
IJIS C 60068-2-431 relative		relative h	ed at 40±2°C, e humidity 80±5%, 5ppm for 96h.						×	_		
COUN	T DE	SCRIPTION	ON OF REVISIONS		DESIG	NED			CHECKED	DATE		
REMARK	L			1			APPRO	VED	NF.MIYAZAKI	17. 0	5. 12	
							CHEC	KED	HS. SAKAMOTO		5. 12	
						DESIGNE		KN. KOBAYASHI		5. 12		
Unless otherwise specified, refer to IEC 60512. DRAWN KN. KOBAYASHI					KN. KOBAYASHI	17. 05. 12						
Note QT:Qualification Test AT:Assurance Test X:Applicable Test				DF	DRAWING NO. ELC-364112-		ELC-364112-9	99-00				
HS.		PECIFICATION SHEET			PART				FH53M-7S-0. 25SHW (99)			
	HIROSE ELECTRIC CO., LTD.				CODE			L580	80-3406-0-99		1/2	

SPECIFICATIONS								
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ				
Solderability	Soldered at solder temperature 245±3°C, for immersion duration 3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.	×	_				
Resistance to soldering heat	1) Reflow soldering: peak tmp. 250°C MAX. reflow tmp. over 230°C within 60 sec. 2) Soldering irons: tmp. 350±10°C for 5±1 sec.	No case-deformation and loose contacts. (note 4)	×					

(note1)

This connector is back flip lock type, and top contact points are available.

(note2)

Do not close the actuator before inserting FPC even after the connector is mounted onto a PCB.

Closing the actuator without FPC could make the contact gap smaller, which increases the FPC insertion force.

(note3)

If pull-up or pull-down force is exepected to be applied to the FPC, stabilize the FPC into PCB or other fixed components.

(note4)

Blisters which may be generated on the housing do not affect product performance.

(note5)

There's a case which FPC/FFC retention force doesn't fulfill the value, because FPC/FFC specification affects the result of

Note QT:Q	ualification Test AT:Assurance Test X:Applicable Test	DRAWIN	IG NO.	ELC-364112-99-00		
HS	SPECIFICATION SHEET	PART NO.	FH53M-7S-0. 25SHW (99)			
110	HIROSE ELECTRIC CO., LTD.	CODE NO	CL580	-3406-0-99	ѝ	2/2